

07-03-01

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: George Hsieh

Title: USING THE WAVE SOLDERING PROCESS TO ATTACH MOTHERBOARD CHIPSET HEAT SINKS

Attorney Docket No.: 884.462US1

PATENT APPLICATION TRANSMITTAL**BOX PATENT APPLICATION**Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ Utility Patent Application under 37 CFR § 1.53(b) comprising:
- ☒ Specification (15 pgs, including claims numbered 1 through 30 and a 1 page Abstract).
- ☒ Formal Drawing(s) (7 sheets).
- ☒ **Signed Combined Declaration and Power of Attorney** (3 pgs).
- ☒ Check in the amount of \$890.00 to pay the filing fee.
- ☒ Assignment of the invention to Intel Corporation (2 pgs) and Recordation Form Cover Sheet.
- ☒ Check in the amount of \$40.00 to pay the Assignment recording fee.

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	30 - 20 =	10	x 18 =	\$180.00
INDEPENDENT CLAIMS	3 - 3 =	0	x 80 =	\$0.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$710.00
TOTAL				\$890.00

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This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.